

## Transistors

# 2.5V Drive Nch+Pch MOSFET

## EM6M1

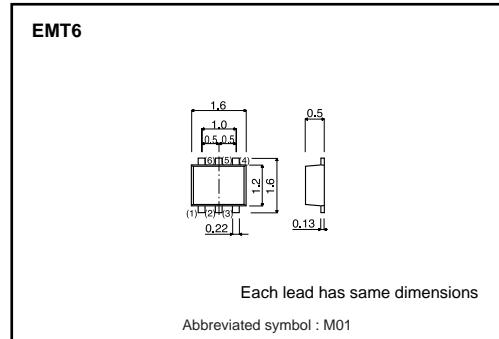
### ●Structure

Silicon N-channel MOSFET /  
Silicon P-channel MOSFET

### ●Features

- 1) Nch MOSFET and Pch MOSFET are put in EMT6 package.
- 2) High-speed switching.
- 3) Low voltage drive (2.5V drive).
- 4) Built-in G-S Protection Diode.

### ●Dimensions (Unit : mm)



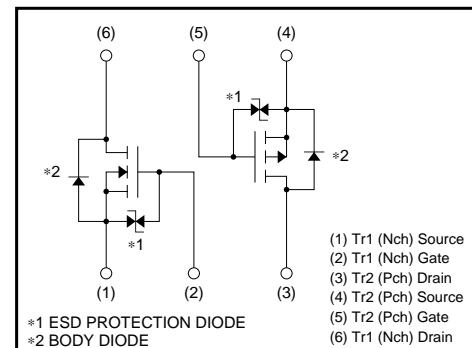
### ●Applications

Switching

### ●Packaging specifications

Type	Package	Taping
	Code	T2R
EM6M1	Basic ordering unit (pieces)	8000

### ●Inner circuit



### ●Absolute maximum ratings ( $T_a=25^\circ C$ )

Parameter	Symbol	Limits		Unit
		Tr1 : N-ch	Tr2 : P-ch	
Drain-source voltage	$V_{DSS}$	30	-20	V
Gate-source voltage	$V_{GSS}$	$\pm 20$	$\pm 12$	V
Drain current	Continuous	$I_D$	$\pm 0.1$	A
	Pulsed	$I_{DP}^{*1}$	$\pm 0.4$	A
Power dissipation	$P_D^{*2}$	150		mW / TOTAL
		120		mW / ELEMENT
Channel temperature	$T_{ch}$	150		$^\circ C$
Range of storage temperature	$T_{stg}$	-55 to +150		$^\circ C$

\*1  $P_w \leq 10\mu s$ , Duty cycle  $\leq 1\%$

\*2 Mounted on a ceramic board

### ●Notice

This product might cause chip aging and breakdown under the large electrified environment.

Please consider to design ESD protection circuit.

## Transistors

**N-ch****●Electrical characteristics (Ta=25°C)**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	—	—	±1	µA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR) DSS</sub>	30	—	—	V	I <sub>D</sub> =10µA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	—	—	1	µA	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS (th)</sub>	0.8	—	1.5	V	V <sub>DS</sub> =3V, I <sub>D</sub> =100µA
Static drain-source on-state resistance	R <sub>DSS (on)</sub> *	—	5	8	Ω	I <sub>D</sub> =10mA, V <sub>GS</sub> =4V
		—	7	13	Ω	I <sub>D</sub> =1mA, V <sub>GS</sub> =2.5V
Forward transfer admittance	Y <sub>fs</sub>   *	20	—	—	mS	V <sub>DS</sub> =3V, I <sub>D</sub> =10mA
Input capacitance	C <sub>iss</sub>	—	13	—	pF	V <sub>DS</sub> =5V
Output capacitance	C <sub>oss</sub>	—	9	—	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	—	4	—	pF	f=1MHz
Turn-on delay time	t <sub>d (on)</sub> *	—	15	—	ns	V <sub>DD</sub> =5V
Rise time	t <sub>r</sub> *	—	35	—	ns	I <sub>D</sub> =10mA
Turn-off delay time	t <sub>d (off)</sub> *	—	80	—	ns	V <sub>GS</sub> =5V
Fall time	t <sub>f</sub> *	—	80	—	ns	R <sub>L</sub> =500Ω
Total gate charge	Q <sub>g</sub> *	—	0.9	—	nC	R <sub>G</sub> =10Ω
Gate-source charge	Q <sub>gs</sub> *	—	0.2	—	nC	V <sub>GS</sub> =4.5V
Gate-drain charge	Q <sub>gd</sub> *	—	0.2	—	nC	R <sub>L</sub> =150Ω, R <sub>G</sub> =10Ω

\*Pulsed

**P-ch****●Electrical characteristics (Ta=25°C)**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	—	—	±10	µA	V <sub>GS</sub> = ±12V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR) DSS</sub>	-20	—	—	V	I <sub>D</sub> = -1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	—	—	-1	µA	V <sub>DS</sub> = -20V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS (th)</sub>	-0.7	—	-2.0	V	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1mA
Static drain-source on-state resistance	R <sub>DSS (on)</sub> *	—	1.0	1.5	Ω	I <sub>D</sub> = -0.2A, V <sub>GS</sub> = -4.5V
		—	1.1	1.6	Ω	I <sub>D</sub> = -0.2A, V <sub>GS</sub> = -4V
		—	2.0	3.0	Ω	I <sub>D</sub> = -0.2A, V <sub>GS</sub> = -2.5V
Forward transfer admittance	Y <sub>fs</sub>   *	0.2	—	—	S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -0.15A
Input capacitance	C <sub>iss</sub>	—	50	—	pF	V <sub>DS</sub> = -10V
Output capacitance	C <sub>oss</sub>	—	5	—	pF	V <sub>GS</sub> = 0V
Reverse transfer capacitance	C <sub>rss</sub>	—	5	—	pF	f=1MHz
Turn-on delay time	t <sub>d (on)</sub> *	—	9	—	ns	V <sub>DD</sub> = -15V
Rise time	t <sub>r</sub> *	—	6	—	ns	I <sub>D</sub> = -0.15A
Turn-off delay time	t <sub>d (off)</sub> *	—	35	—	ns	V <sub>GS</sub> = -4.5V
Fall time	t <sub>f</sub> *	—	45	—	ns	R <sub>L</sub> = 100Ω
Total gate charge	Q <sub>g</sub> *	—	1.2	—	nC	R <sub>G</sub> = 10Ω
Gate-source charge	Q <sub>gs</sub> *	—	0.2	—	nC	V <sub>GS</sub> = -4.5V
Gate-drain charge	Q <sub>gd</sub> *	—	0.2	—	nC	R <sub>L</sub> = 75Ω, R <sub>G</sub> = 10Ω

\*Pulsed

## Transistors

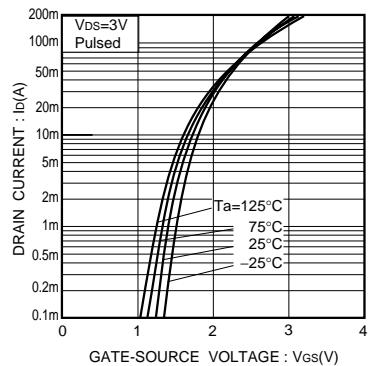
**N-ch****●Electrical characteristic curve**

Fig.1 Typical Transfer Characteristics

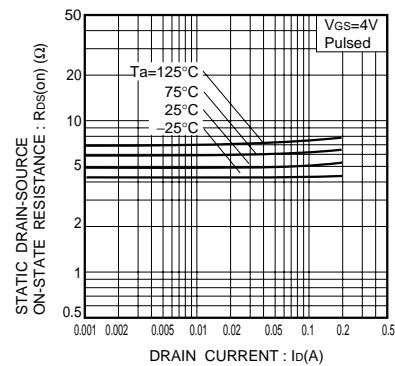


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current ( I )

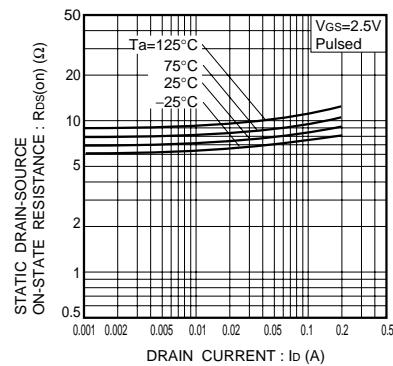


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current ( II )

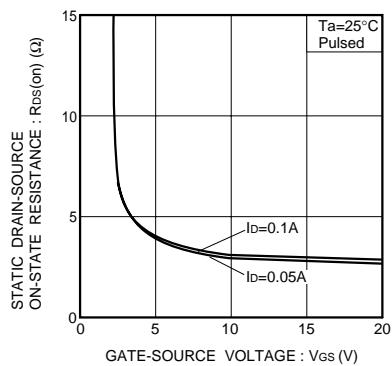


Fig.4 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

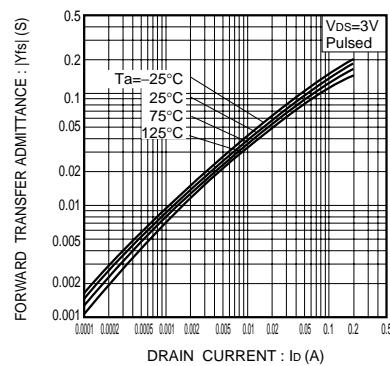


Fig.5 Forward Transfer Admittance vs. Drain Current

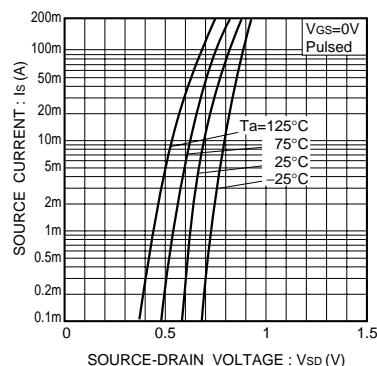


Fig.6 Reverse Drain Current vs. Source-Drain Voltage ( I )

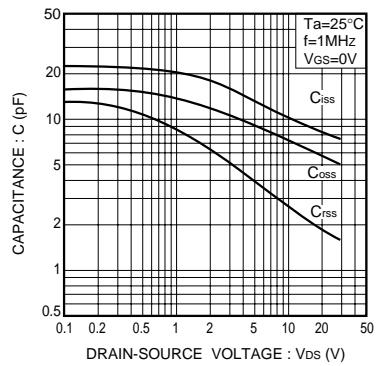


Fig.7 Typical Capacitance vs. Drain-Source Voltage

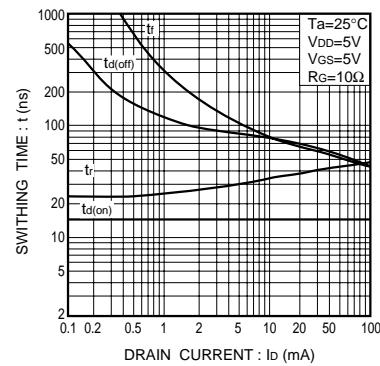


Fig.8 Switching Characteristics

## Transistors

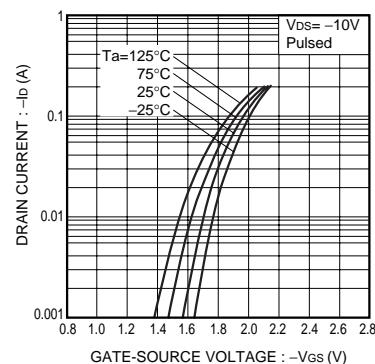
**P-ch****●Electrical characteristic curve**

Fig.1 Typical Transfer Characteristics

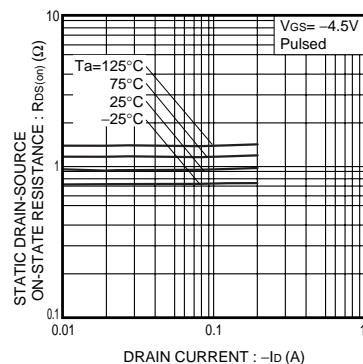


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current ( I )

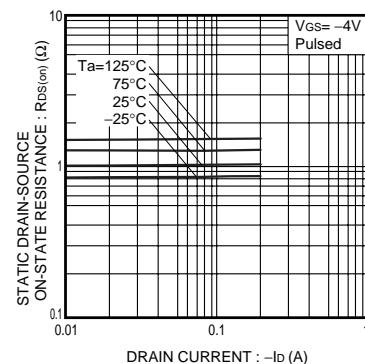


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current ( II )

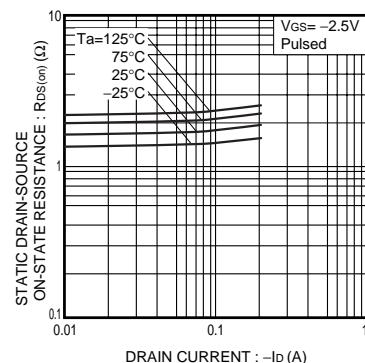


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current ( III )

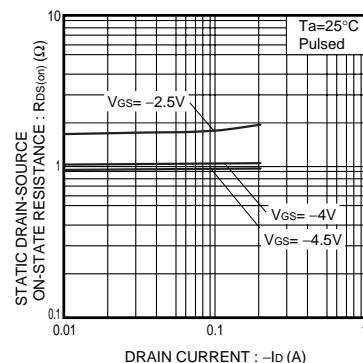


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current ( IV )

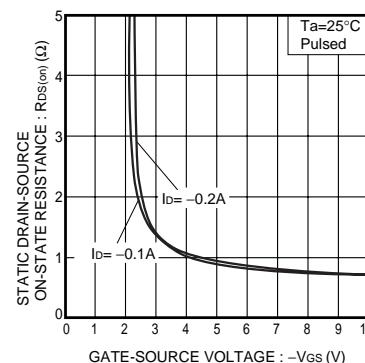


Fig.6 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

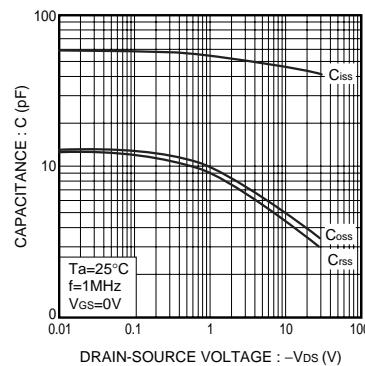


Fig.7 Typical Capacitance vs. Drain-Source Voltage

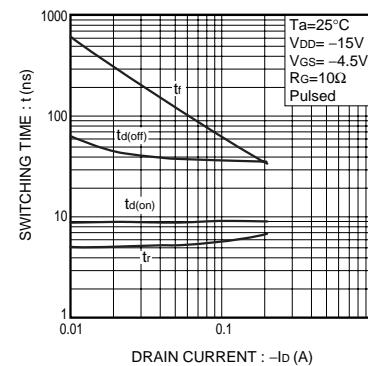


Fig.8 Switching Characteristics

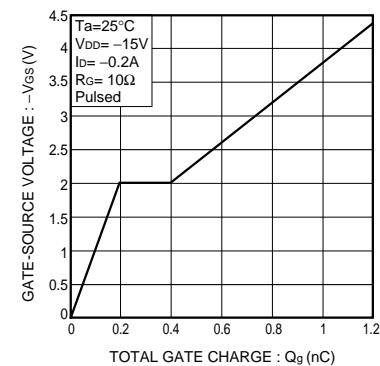


Fig.9 Dynamic Input Characteristics

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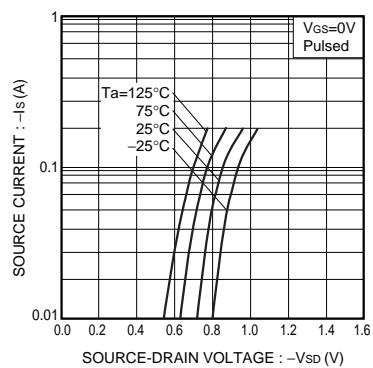


Fig.10 Source Current vs. Source-Drain Voltage

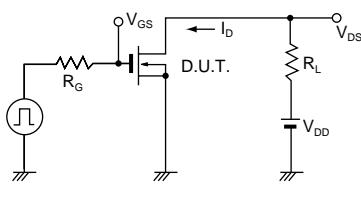
**N-ch****●Measurement circuit**

Fig.9 Switching Time Test Circuit

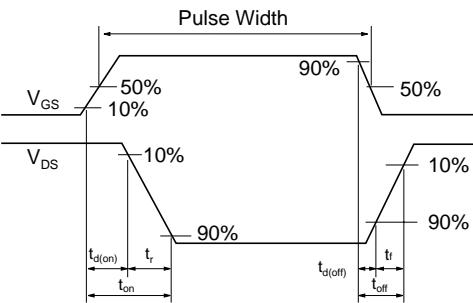


Fig.10 Switching Time Waveforms

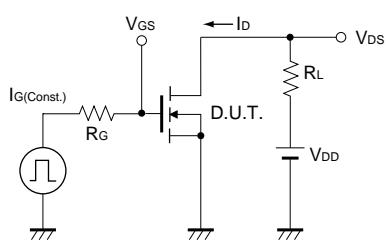


Fig.11 Gate Charge Measurement Circuit

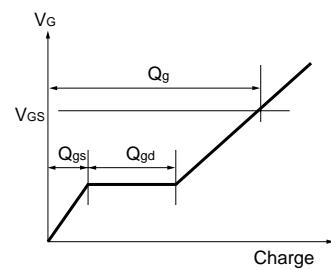


Fig.12 Gate Charge Waveform

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P-ch

### ● Measurement circuit

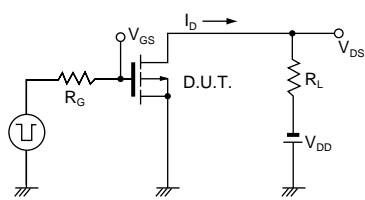


Fig.11 Switching Time Test Circuit

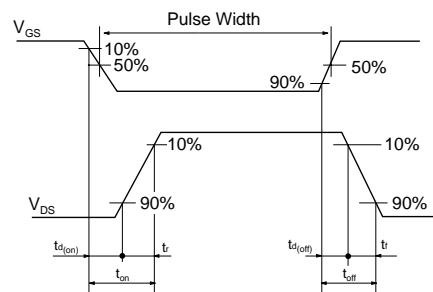


Fig.12 Switching Time Waveforms

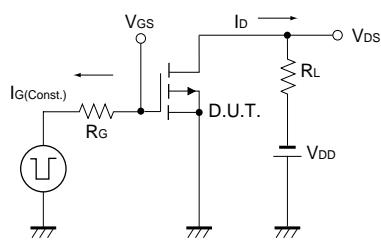


Fig.13 Gate Charge Measurement Circuit

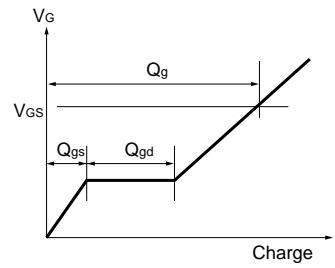


Fig.14 Gate Charge Waveform

## Appendix

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### Notes

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